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SUBMIT A PAPER FOR SEMI-THERM 40!

As you further develop a technique or application, consider documenting it for the thermal community. **SEMI-THERM 40** will begin accepting abstracts during the summer (deadline is September 15, 2023). We welcome your submissions! Visit us at www.semi-therm.org.

SEMI-THERM 40 is March 20-24, 2024 – be there!

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